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Log No. 33054

RESEARCH AND DEVELOPMENT BOARD

Copy No. 42

Committee on Electronics
Panel on Components

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25 April 1949

AGENDA

Fifteenth Meeting to be held
9, 10 May 1949 at 1000 D.S.T.
Room 3D-564, National Defense Building (Pentagon)
Washington, D. C.
(Reception Desk 3E-648)

Item 1. Approval of Minutes - Fourteenth Meeting

Item 2. Mobilization Plan for the Electronics Equipment Industry

At the 18th Meeting of the Committee on Electronics, the Committee requested the Chairman of the Panel to prepare a study of the Munitions Board report prepared by the Electronics Equipment Industry Advisory Committee. The Chairman will comment on the subject report as it affects the scope of the Panel.

Item 3. Master Plan of Research and Development in the National Military Establishment

At the 19th Meeting, the Research and Development Board approved the "Master Plan of R & D in the NME" with subsequent approval by the Secretary of Defense on 1 March 1949. Attached herewith is RDB 169/1 "Classification System for the Master Plan" and EL 127/1 which is a condensed review of the Plan prepared by the Secretariat of the Committee on Electronics. The Committee has requested its Panels to comment on the Master Plan especially with regard to the importance rating assigned Technical Objective SR-6 which is of particular concern to the Panel on Components.

Item 4. Allocation of Responsibility for Components R & D Program

At the last meeting of the Panel, the Chairman requested all Sub-panel Chairmen to prepare a memorandum outlining the pattern for assignment of responsibility in accordance with RDB 133/2, EL 120/1 and EL 120/2 previously circulated. Each Subpanel Chairman will discuss his proposed scheme for allocation. Attached as LCP 32/1 is a memorandum from the Chairman to the Acting Executive Director for the Committee on Electronics.

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Item 5. Organization

- 5.1 Revision of field of interest for the Subpanel on RF Transmission Lines.
 - 5.1.1 Assignment of responsibility for magnet and hook-up wire.
 - 5.1.2 Dissolution of ANRFCCC and all activities being coordinated by this Committee be pursued by RDB and ASES.A.
- 5.2 Approval of directive and membership for the Subpanel on Miniature Components and Packaged Sub-Assemblies.
- 5.3 Proposed reactivation of a Subpanel on Shock and Vibration.
- 5.4 Cognizance for coaxial DC power connectors.
- 5.5 Cognizance for rotary devices (motors, dynamos, etc).
- 5.6 Assignment of magnetic amplifiers and high frequency power supplies.
- 5.7 Assignment of responsibility for semi-conductors.

Item 6. Other Business

Item 7. Date and Place of Next Meeting

Note: The Panel will reconvene at the Bureau of Standards on 10 May for lectures and discussions by Bureau of Standards' personnel.

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- 1. RDB 169/1
- 2. EL 127/1
- 3. LCP 32/1

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RESEARCH AND DEVELOPMENT BOARD
Committee on Electronics

LCP 32/1

April 15, 1949

MEMORANDUM FOR: H. W. Serig
Colonel, USAF
Acting Exec. Director
Committee on Electronics
Research & Development Board
Washington 25, D. C.

SUBJECT : Allocation of Responsibility for Research and
Development Programs

This replies to your letter of 10 March 1949 on the above subject.

The Panel on Components and its Sub-Panels consider that they have been complying with the spirit of the Board policy expressed in RDB 133/2 throughout their activities. From the start they have considered that the allocation of responsibility on each specific project is an inescapable function and they have worked out a method for allocating to one of the three services the responsibility for conducting or contracting to industry, each specific development project.

This has been done by the Subpanels on a voluntary agreement basis among the service representatives on the Subpanels. The factors considered in arriving at such "voluntary" allocations are: availability of funds; availability of competent personnel or supervision of the development; the service (if any) proposing the project; the service having prime interest in the outcome of the project; relation of the new project to previous projects allocated earlier and the urgency of the schedule. To date the Subpanels have been quite successful in securing voluntary acceptance and in making allocations of specific projects once the technical requirements involved had been resolved and agreed upon. As brought out in our recent

Annual Report, there are, of course, cases where circumstances prevent or delay the actual undertaking of the project due to internal matters within a given service in allocating development funds. If these delays persist it is conceivable that the Subpanels may need to review certain projects and make appropriate reallocation.

This method may depart from the concepts set forth in RDB 133/2 in respect to method of allocation which appears to contemplate allocation on some broad basis related to operational or functional missions. The Panel considers that in the field of components it is impossible and impractical to take into account such factors and considers that its allocations must be made wholly on the basis of the capabilities and technical "know-how" of some one of the three services. Because of historical background these latter factors do not, at the present time, appear to be related in any way to the operational or purchase functions of the services. It has recognized, however, the long standing arrangements between the Air Force and Signal Corps under which the Signal Corps has carried the responsibility for a major share of the development on components or electronic equipment.

The allocations arrived at by the Subpanels are recorded on the Summary Charts which are submitted once a year to the Committee on Electronics.

F. J. Given, Chairman
Panel on Components